Notice for TAIYO YUDEN products

Please read this notice before using the TAIYO YUDEN products.

/!\ REMINDERS

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- Please contact Taiyo Yuden Co., Ltd. for further details of product specifications as the individual specification is available.
- Please conduct validation and verification of products in actual condition of mounting and operating environment before commercial shipment of the equipment.
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Do not incorporate the products into any equipment in fields such as aerospace, aviation, nuclear control, submarine system, military, etc. where higher safety and reliability are especially required.

In addition, even electronic components or functional modules that are used for the general electronic equipment, if the equipment or the electric circuit require high safety or reliability function or performances, a sufficient reliability evaluation check for safety shall be performed before commercial shipment and moreover, due consideration to install a protective circuit is strongly recommended at customer's design stage.

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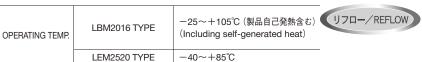
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Should you have any question or inquiry on this matter, please contact our sales staff.

信号系巻線チップインダクタ **WOUND CHIP INDUCTORS** FOR SIGNAL LINE

LB SERIES M TYPE

LE SERIES M TYPE











OPERATING TEMP.	LBM2016 TYPE	(Including self-generated heat)
	LEM2520 TYPE	-40~+85°C

FEATURES

LBM2016

・下面電極構造を採用により、高いQ化および狭公差化を実現しました。 信号系用途の回路設計に適した巻線チップインダクタです。

LEM2520

・アキシャルリード形インダクタの製造工程・基本構造を継承した量産性 に優れた高品質のインダクタ

LBM2016 Series

· High Q and narrow tolerance are achieved by adopting bottom-surface electrode structure. Wound Chip Inductors that are suit for module design of signal line uses.

LEM2520 Series

· A high-quality inductor that is simple to mass-produce and conforms to the same production process and basic construction as an axial lead type inductor.

用途 APPLICATIONS

・DSC / DVC / HDD、液晶、携帯電話、ゲーム機器、各種映像機器、各種 通信機器など

· DSC/DVC/HDD, LCD, portable telephones, game equipments. Various audio-visual equipments, various communication equipments, etc.

形名表記法 ORDERING CODE



形式	
LBM	信号系巻線チップインダクタ
LEM	信号系巻線チップインダクタ



梱包	
Т	テーピング



公称イ	ンダクタンス〔μH〕
例	
R12	0.12
1R0	1.00
100	10.0

インダ	クタンス許容差
J	±5%
K	±10%



外形寸法 [mm]	
2016	2.0×1.6
2520	2.5×2.0

当社管理記号	
\triangle	標準品



Туре	
LBM	Wound chip inductor for signal line
LEM	Wound chip inductor for signal line

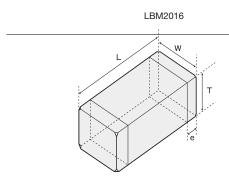
Packaging	
T	Tape & Reel

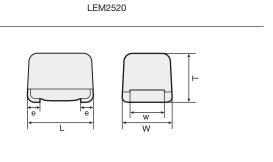
Nominal Inductance(µH)		
example		
R12	0.12	
1R0	1.00	
100	10.0	

Inductance Tolerances		
J	±5%	
K	±10%	

External Dimensions (mm)		
2016	2.0×1.6	
2520	25×20	

0	
Internal	code
\triangle	Standard Products
	△=Blank space



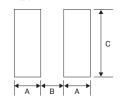


Type	L W		Т	е	w
LBM2016	2.0±0.2	1.6±0.2	1.6±0.2	0.5±0.2	
LBIVIZUTO	(0.08±0.008)	(0.063±0.008)	(0.063±0.008)	(0.02 ± 0.008)	
LEM2520	2.5±0.2	2.0±0.2	1.8±0.2	0.45	1.4±0.1
LEIVIZ520	(0.098±0.008)	(0.079±0.008)	(0.071±0.008)	(0.018)	(0.055±0.004)

推奨ランドパターン Recommended Land Patterns

実装上の注意

- ・実装状態を確認の上ご使用下さいますようお願いいたします。
- ・本製品のはんだ付けは、リフローはんだ工法に限ります。 (LBのみの適用)
- ・推奨ランドパターン

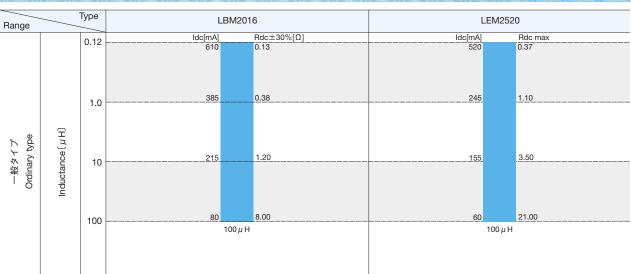


			Unit: mr
TYPE	Α	В	С
LBM2016	0.7	0.8	1.8
LEM2520	0.9	1.5	1.5

Unit: mm (inch)

- Surface Mounting
- ${\boldsymbol \cdot}$ Mounting and soldering conditions should be checked beforehand.
- Applicable soldering process to this products is reflow soldering only.
 (LB only)
- · Recommended Land Patterns

概略バリエーション AVAILABLE INDUCTANCE RANGE



	Inductance	ldc[n	nA]	$Rdc[\Omega]$			
迴 s		LBM2016	LEM2520	LBM2016	LEM2520		
表 催 mples		(max.)	(max.)	(±30%)	(max.)		
	0.12 μ H	610	520	0.13	0.37		
£ Exa	1.00 μ H	385	245	0.38	1.10		
~ –	10.0 μ H	215	155	1.20	3.50		
	100 μ H	80	60	8.00	21.0		

セレクションガイド Selection Guide

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アイテム一覧 Part Numbers

Electrical Characteristics

梱包 Packaging 信頼性 Reliability Data 使用上の注意 Precautions

etc

TAIYO YUDEN 2009

アイテム一覧 PART NUMBERS

LBM2016 TYPE —

形名	EHS	公称	インダクタンス	0/#	自己共振 周波数	直流抵抗	定格電流	測定
70 - 1	(Environmental	インダクタンス	許容差	Q値 Q VALUE	同 版 剱 Self-resonant	DC Resistance	Rated	周波数
	Hazardous	Inductance	Inductance	(min.)	frequency [MHz]	Resistance (Ω)	current (mA)	Measuring frequency
Ordering code	Substances)	(μH)	Tolerance	(11111117)	min.	±30%	(max.)	(MHz)
LB M2016TR12J	RoHS	0.12			600	0.13	610	, ,
LB M2016TR15J	RoHS	0.15			550	0.15	570	
LB M2016TR18J	RoHS	0.18			500	0.15	560	
LB M2016TR22J	RoHS	0.22			450	0.20	520	
LB M2016TR27J	RoHS	0.27			425	0.21	510	
LB M2016TR33J	RoHS	0.33			400	0.21	490	25.2
LB M2016TR39J	RoHS	0.39			375	0.26	440]
LB M2016TR47J	RoHS	0.47]		350	0.26	430	
LB M2016TR56J	RoHS	0.56			300	0.29	410	
LB M2016TR68J	RoHS	0.68			270	0.32	400	
LB M2016TR82J	RoHS	0.82		30	250	0.34	390	
LB M2016T1R0J	RoHS	1.0			220	0.38	385	
LB M2016T1R2J	RoHS	1.2	±5%		180	0.41	370]
LB M2016T1R5J	RoHS	1.5			135	0.47	350	1
LB M2016T1R8J	RoHS	1.8	1		100	0.48	345	1
LB M2016T2R2J	RoHS	2.2			75	0.54	340	
LB M2016T2R7J	RoHS	2.7			55	0.59	310	7.96
LB M2016T3R3J	RoHS	3.3			48	0.68	290	
LB M2016T3R9J	RoHS	3.9			43	0.74	275	1
LB M2016T4R7J	RoHS	4.7	1		40	0.78	270	
LB M2016T5R6J	RoHS	5.6			36	0.88	255]
LB M2016T6R8J	RoHS	6.8	1		33	0.97	240	1
LB M2016T8R2J	RoHS	8.2			30	1.10	225	
LB M2016T100J	RoHS	10	1		27	1.20	215	
LB M2016T120J	RoHS	12		0.5	23	1.4	200	1
LB M2016T150J	RoHS	15	-	25	20	1.5	190	
LB M2016T180J	RoHS	18			18	2.5	150	
LB M2016T220J	RoHS	22			17	2.8	140	
LB M2016T270J	RoHS	27			16	3.2	130	2.52
LB M2016T330J	RoHS	33			15	3.6	125	
LB M2016T390J	RoHS	39			14	3.9	120]
LB M2016T470J	RoHS	47			13	4.1	115	
LB M2016T560J	RoHS	56		20	12	5.9	95	
LB M2016T680J	RoHS	68			11	7.0	90	
LB M2016T820J	RoHS	82			10	7.7	85	
LB M2016T101J	RoHS	100		15	9.0	8.0	80	0.796

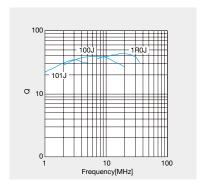
LEM2520 TYPE -

		1						
形名	EHS	公称	インダクタンス		自己共振 周波数	直流抵抗	定格電流	測定
–	(Environmental	インダクタンス	許容差	Q	Self-resonant	DC Resistance	Rated current	周波数 Measuring
Ordering code	Hazardous	Inductance	Inductance	min.	frequency (MHz)	(Ω)	(mA)	frequency
	Substances)	(µ H)	Tolerance		min.	max.	max.	(MHz)
LEM 2520 TR12K	RoHS	0.12			600	0.37	520	
LEM 2520 TR15K	RoHS	0.15			550	0.42	480	
LEM 2520 TR18K	RoHS	0.18			500	0.46	460	
LEM 2520 TR22K	RoHS	0.22			450	0.52	430	
LEM 2520 TR27K	RoHS	0.27			425	0.56	420	
LEM 2520 TR33K	RoHS	0.33	±10%		400	0.60	400	25.2
LEM 2520 TR39K	RoHS	0.39			375	0.65	375	
LEM 2520 TR47K	RoHS	0.47			350	0.68	350	
LEM 2520 TR56K	RoHS	0.56			300	0.75	325	
LEM 2520 TR68K	RoHS	0.68		30	270	0.85	300	
LEM 2520 TR82K	RoHS	0.82		30	250	1.00	260	
LEM 2520 T1R0J	RoHS	1.0			220	1.10	245	
LEM 2520 T1R2J	RoHS	1.2			180	1.20	230	
LEM 2520 T1R5J	RoHS	1.5			135	1.30	220	
LEM 2520 T1R8J	RoHS	1.8			100	1.45	210	
LEM 2520 T2R2J	RoHS	2.2			75	1.55	200	7.96
LEM 2520 T2R7J	RoHS	2.7			55	1.70	195	
LEM 2520 T3R3J	RoHS	3.3			48	1.90	185	7.90
LEM 2520 T3R9J	RoHS	3.9			43	2.10	180	
LEM 2520 T4R7J	RoHS	4.7			40	2.30	175	
LEM 2520 T5R6J	RoHS	5.6			36	2.50	170	
LEM 2520 T6R8J	RoHS	6.8			33	2.70	165	
LEM 2520 T8R2J	RoHS	8.2			30	3.05	160	
LEM 2520 T100J	RoHS	10	±5%		27	3.50	155	
LEM 2520 T120J	RoHS	12		25	23	3.80	150	
LEM 2520 T150J	RoHS	15		20	20	4.40	140	
LEM 2520 T180J	RoHS	18			18	4.80	130	
LEM 2520 T220J	RoHS	22			17	5.50	125	
LEM 2520 T270J	RoHS	27			16	6.30	115	2.52
LEM 2520 T330J	RoHS	33			15	7.10	110	2.52
LEM 2520 T390J	RoHS	39			14	9.50	90	
LEM 2520 T470J	RoHS	47			13	11.10	80	
LEM 2520 T560J	RoHS	56		20	12	12.10	75	
LEM 2520 T680J	RoHS	68			11	16.60	70	
LEM 2520 T820J	RoHS	82			10	19.00	65	
LEM 2520 T101J	RoHS	100		15	9	21.00	60	0.796

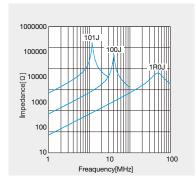
特性図 ELECTRICAL CHARACTERISTICS

●LBM2016

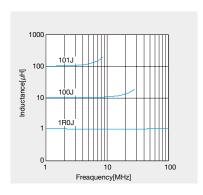
Q-周波数特性 Q-Characteristics



インピーダンス周波数特性 Impedance-vs-Frequency characteristics

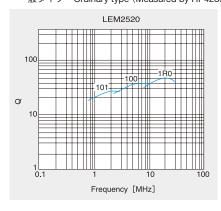


インダクタンス周波数特性 Inductance-vs-Frequency characteristics・

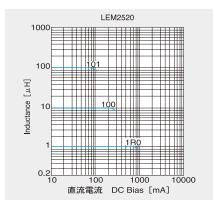


●LEM2520

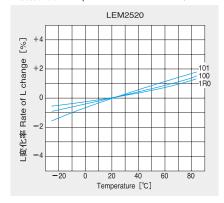
Q-周波数特性例 Q-Characteristics -一般タイプ Ordinary type (Measured by HP4285A+42851A)



直流重量特性例 DC Bias characteristics (Measured by HP4285A+42841A)



温度特性例 Temperature characteristics (Measured by HP4285A+42851A)

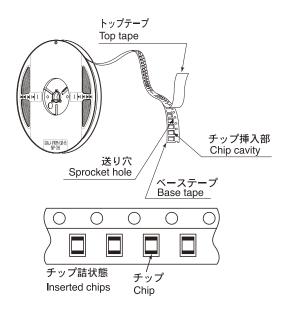


①最小受注単位数 Minimum Quantity

		上 数量		
形式	Standard	d Quantity ^[pcs]		
Туре	紙テーピング	エンボステーピング		
	Papar Tape	Embossed Tape		
CBC3225	_	1000		
LB3218	_	2000		
LBR2518/LBC2518/LB2518		0000		
/CB2518/CBC2518/LEM2520	_	2000		
LBM2016/LBC2016/LB2016		2000		
/CB2016/CBC2016		2000		
LB2012/LBC2012/LBR202	_	3000		
/CB2012/CBC2012		3000		
CBL2012	4000	_		
LB1608	4000	_		
LBMF1608/CBMF1608	_	3000		
-				

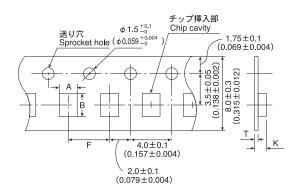
②テーピング材質 Tape material

エンボステープ Embossed tape



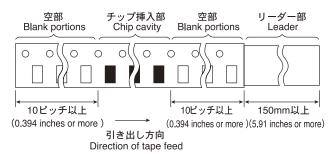
③テーピング寸法 Taping Dimensions

エンボステープ (8mm幅) Embossed Tape (0.315 inches wide) 紙テープ (8mm幅) Card board carrier tape (0.315 inches wide)

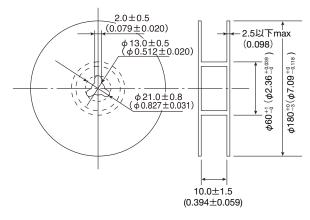


形式	チップ	挿入部	挿入ピッチ	テーフ	プ厚み
	Chip	cavity	Insertion pitch	Tape thickness	
Type	Α	В	F	Т	K
L DM 0016	1.9±0.2	2.2±0.2	4.0±0.1	0.3	2.15
LBM 2016	(0.075±0.008)	(0.087±0.008)	(0.157±0.004)	(0.012)	(0.085)
L EM 0500	2.3±0.1	2.7±0.1	4.0±0.1	0.3	2.10
LEM 2520	(0.091±0.004)	(0.106±0.004)	(0.157±0.004)	(0.012)	(0.083)
CBC3225	2.8±0.1	3.5±0.1	4.0±0.1	0.6max	4.0max
CBC3225	(0.110±0.004)	(0.138±0.004)	(0.157±0.004)	(0.024)	(0.157)
LB3218	2.1±0.1	3.5±0.1	4.0±0.1	0.3	2.3max
LB3216	(0.084±0.004)	(0.014±0.004)	(0.157±0.004)	(0.012)	(0.092)
LB2518 / CB2518	2.15±0.2	2.7±0.2	4.0±0.1	0.3	2.10
LBC2518 / CBC2518	(0.085±0.008)	(0.107±0.008)	(0.157±0.004)	(0.012)	(0.083)
LBR2518	(0.005±0.006)	(0.107 ±0.006)	(0.157±0.004)	(0.012)	(0.063)
LB2016/ CB2016	1.9±0.2	2.2±0.2	4.0±0.1	0.3	2.15
LBC2016 / CBC2016	(0.075±0.008)	(0.087±0.008)	(0.157±0.004)	(0.012)	(0.085)
LB2012 / CB2012	1.45±0.2	2.25±0.2	4.0±0.1	0.25	2.0
LBC2012 / CBC2012	(0.058±0.008)	(0.09±0.008)	(0.157±0.004)	(0.012)	(0.079)
LBR2012	(0.030±0.006)	(0.09±0.006)	(0.157±0.004)	(0.012)	(0.079)
CBL2012	1.55±0.2	2.3±0.2	4.0±0.1	1.1max	1.1max
GBL2012	(0.061±0.008)	(0.091±0.008)	(0.157±0.004)	(0.044)	(0.044)
L D1000	1.0±0.2	1.8±0.2	4.0±0.1	1.1max	1.1max
LB1608	(0.059±0.008)	(0.072±0.008)	(0.157±0.004)	(0.044)	(0.044)
LBMF1608 /	1.1±0.1	1.9±0.1	3.5±0.05	0.3max	1.6max
CBMF1608	(0.04±0.004)	(0.076±0.004)	(0.14±0.002)	(0.012)	(0.064)

④リーダー部/空部 Leader and Blank Portion

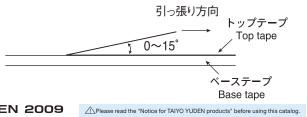


⑤リール寸法 Reel Size



⑥トップテープ強度 Top Tape Strength

トップテープのはがし力は、下図矢印方向に τ 0.1 \sim 0.7Nと τ 0 τ 0 ます。 The top tape requires a peel-off force 0.1 to 0.7N in the direction of the arrow as illustrated below.



					Specified Value	10				
		LB3218			Specified Valu					
Item	LEM2520	LB3218 LB2518 LB2016 LB2012 LB1608 LBMF1608	LBC2518 LBC2016 LBC2012	LBR2518 LBR2012	CB2518 CB2016 CB2012	CBC3225 CBC2518 CBC2016 CBC2012	CBL2012	CBMF1608	LBM2016	Test Methods and Remarks
1.Operating tem- perature Range	-40~+85°C		°C (Including	self-generated	I heat)					
2.Storage	-40~+85°C									
3.Rated Current	Within the spo	ecified toleran	ice							LEM·LB·LBC·LBMF·LBM Series The maximum DC value having inductance decrease within 10% and temperature increase within 20°C by the application of DC bias. LBR Series The maximum DC value having inductance decrease within 20% and temperature increase within 20°C by the application of DC bias. CB·CBC·CBL·CBMF Series The maximum DC value having inductance decrease within 30% and temperature increase within 30% and temperature increase within 40°C by the application of DC bias.
4.Inductance	Within the spo	ecified toleran	nce							LEM Series R12~101: Measuring equipment: LCR Meter (HP4285A+42851A or its equivalent) Measuring frequency: Specified frequency LB·LBC·LBR·CB·CBC·CBL·LBMF· CBMF·LBM Series: Measuring equipment: LCR Mater (HP4285A or its equivalent)
5.Q	Within the specified tolerance								Within the specified tolerance	LEM Series R12~101: Measuring equipment: LCR Meter (HP4285A+42851A or its equivalent) Measuring frequency: Specified frequency LBM Series: Measuring equipment: LCR Mater (HP4285A or its equivalent)
6.DC Resisitance	Within the sp	ecified toleran	nce							LEM+LB+LBC+LBR+CB+CBC+CBL+LBM+ LBMF+CBMF Series: Measuring equipment: DC Ohmmeter (HIOKI 3227 or its equivalent)
7.Self-Resonant Frequency	Within the sp	ecified toleran	nce							LEM2520: Measuring equipment: Impedance analyzer (HP4291A or its equivalent) LB · LBC · LBR · CB · CBC · CBL · LBMF · CBMF Series: Measuring equipment: Impedance analyzer (HP4291A or its equivalent) LBM Series: Measuring equipment: Network analyzer (HP8720B or its equivalent)

		1,00040			Specified Value	9					
Item	LEM2520	LB3218 LB2518 LB2016 LB2012 LB1608 LBMF1608	LBC2518 LBC2016 LBC2012	LBR2518 LBR2012	CB2518 CB2016 CB2012	CBC3225 CBC2518 CBC2016 CBC2012	CBL2012	CBMF1608	LBM2016	Te	est Methods and Remarks
8.Temperature Char-	Inductance change:	Inductance change:	LBC2518	Inductance change:	Inductance change:	CBC3225	Inductance change:	Inductance change:	Inductance change:	Change of	of maximum inductance deviation
acteristic	Within±5%	Within±15%	LBC2016	Within±15%	Within±15%	CBC2518	Within±15%	Within±20%	Within±5%	in step 1	-5
			Inductance change:			CBC2016					
		LBMF1608	Within±20%			Inductance change:					
		LB3218				Within±20%				Step	Temperture (°C)
		Inductance change:	LBC2012							1	20
		Within±20%	Inductance change:			CBC2012				2	-25
			Within±30%			Inductance change:				3	20 (Reference temperature)
						Within±30%				4	+85 (Maximum operating temperature)
										5	20
9.Rasistance to Flex-	No damage.									Warp: 2m	nm (LB, LBC, LBR, CB, CBC, CBL,
ure of Substrate											LBM,LBMF, CBMF Series)
										: 3n	nm (LEM2520)
										Test subs	strate: Printed board
										According	g to JIS C0051
											Pressig jig
											10 20 Thickness
											R340 LB·LBMF· CBMF1608
											: 0.8mm Others : 1.0mm
											→ Board L
										R5	
											45±2mm >
10.Body Strength	No damage.									LB·LBC·I	LBR · CB · CBC · CBL · LBM · LEW2520
										Applied for	orce: 10N
										Duration	: 10sec.
										LB1608 •	LBMF1608 · CBMF1608
										Applied for	orce: 5N
										Duration	: 10sec.
11.Self Resonant	Inductance of	change : Within	10%	Inductance change:	Inductance of	hange : Within	1-30%		Inductance change:	Measure i	inductance with application of rated
Freguency				Within-20%					Within-10%	current us	ing LCR metre to cpmpare it with the
										initial value	э.
12.Adhesion of termi-	No abnorma	lity.								TB.TBC.	LBR · CB · CBC · CBL · LBM · LBMF
nal electrode										·CBMF·L	_EM2520
										Applied for	orce: 10N to X and Y directions
										Duration	
											strate : Printed board
13.Resistance to	Inductance change:		hange : Within						Inductance change:		3 · LBC · LBR · CB · CBC · CBL ·
vibration	Within±5%	No significan	it abnormality i	n appearance.					Within±5%		MF · CBMF :
	No signifi-								No signifi-		g to JIS C5102 clause 8.2.
	cant abnor-								cant abnor-	Vibration	
	mality in								mality in	Direction	s: 2 hrs each in X, Y and Z di-
	appearance.								appearance.	F	rections. Total: 6 hrs
											y range: 10 to 55 to 10 Hz (1min.)
											e: 1.5mm
											method: Soldering onto printed board
										Hecover	ry: At least 2 hrs of recovery
											under the standard condition
											after the test, followed by the
											measurement within 48 hrs.

				5	Specified Value	е				
Item	LEM2520	LB3218 LB2518 LB2016 LB2012 LB1608 LBMF1608	LBC2518 LBC2016 LBC2012	LBR2518 LBR2012	CB2518 CB2016 CB2012	CBC3225 CBC2518 CBC2016 CBC2012	CBL2012	CBMF1608	LBM2016	Test Methods and Remarks
14.Drop test	Inductance change: Within±5% No significant abnormality in appear- ance.									LEM: Acceleration: 980m/sec² Duration: 6msec Number of times: 6 sides × 3 times Mounting method: Soldering onto printed board Recovery: At least 2 hrs of recovery under the standard condition after the test, followed by the measurement within 48 hrs.
15.Solderability	At least 90%	of surface of t	terminal electro	ode is covered	by new solder					LEM: Solder temperature: 230±5°C Duration: 5±0.5sec. Flux: Methanol solution with 25% of colophony LB·LBC·LBR·CB·CBC·CBL·LBM· LBMF·CBMF: Solder temperature: 245±5°C Duration: 5±0.5sec Flux: Methanol solution with 25% of
16.Resisitance to soldering heat	Inductance change: Within±10% No significant abnormality in appearance.	LB1608 Inductance change: Within±10% No significant abnormality in appear- ance. LBMF1608 Inductance change: Within±20% No significant abnormality in appear- ance.	No significan	hange : within t abnormality i				Inductance change: Within±20% No significant abnormality in appearance.	Inductance change: Within±5% No significant abnormality in appear- ance.	colophony LEM: Reflow condition 3 times of reflow over at 220±5°C for 40sec. MAX, With Peak temperature at 240±5°C for 5 sec. MAX. (Refer to a Profile of chart below.) 200 220 220 220 220 220 220 220 220 2
solvent	No significan	it abnormality i	n appearance							Type of solvent: Isopropyl alcohol (LEM2520 · LB · LBC · LBR · CB · CBC · CBL · LBM · LBMF · CBMF) Cleaning conditions: 90s. Immersion and cleaning. (LEM520 · LB · LBC · LBR · CB · CBC · CBL · LBM · LBMF · CBMF)

				ç	Specified Valu	Je				
Item		LB3218 LB2518	I DOOS : 5			CBC3225				Test Methods and Remarks
item	LEM2520	LB2016 LB2012 LB1608 LBMF1608	LBC2518 LBC2016 LBC2012	LBR2518 LBR2012	CB2518 CB2016 CB2012	CBC2518 CBC2016 CBC2012	CBL2012	CBMF1608	LBM2016	lest Methods and Herharks
18.Thermal shock	Inductance change: Within±10% Q→ R12~4R7: 30min. 5R6~330: 25min. 390~820: 20min. 101:15min.	Inductance	c change :Withi ant abnormalit	in±10% y in appearanc	e.					LEM: Conditions for 1 cycle Step Temperature (°C) Duration (min) 1
19.Damp heat	Inductance change: Within±10% Q→ R12~4R7: 30min. 5R6~330: 25min. 390~820: 20min. 101:15min.		change :Withi	in±10% y in appearanc	e.					Temperature: 60±2°C Humidity: 90~95%RH Duration: 1000 hrs Recovery: At least 2 hrs of recovery under the standard condition after the test, followed by the measure- ment within 48 hrs.
20.Loading under damp heat	Inductance change: Within±10% Q→ R12~4R7: 30min. 5R6~330: 25min. 390~820: 20min. 101:15min.		change : With	in±10% y in appearanc	e.					LEM · LB · LBC · CB · CBC · CBL · LBM · LBMF · CBMF : Temperature : 60±2°C Humidity : 90~95%RH Duration : 1000 hrs Applied current : Rated current Recovery : At least 2 hrs of recovery under the standard condition after the test, followed by the measure- ment within 48 hrs.
21.High temperature life test	Inductance change: Within±10% Q→ R12~4R7: 30min. 5R6~330: 25min. 390~820: 20min. 101:15min.					ctance change ignificant abnor		arance.		LEM · CB · CBC · CBL · LBM · CBMF : Temperature : 85±2°C Duration : 1000 hrs Recovery : At least 2 hrs of recovery under the standard condition after the test, followed by the measurement within 48 hrs.
22.Loading at high temperature			change :Withi	in±10% y in appearanc	е.					LB·LBC·LBR·LBMF: Temperature: 85±2°C Duration: 1000 hrs Applied current: Rated current Recovery: At least 2 hrs of recovery under the standard condition after the test, followed by the measure- ment within 48 hrs.

	Specified Value									
Item	LEM2520	LB3218 LB2518 LB2016 LB2012 LB1608 LBMF1608	LBC2518 LBC2016 LBC2012	LBR2518 LBR2012	CB2518 CB2016 CB2012	CBC3225 CBC2518 CBC2016 CBC2012	CBL2012	CBMF1608	LBM2016	Test Methods and Remarks
23.Low temperature	Inductance change :									
life test	Within±10%	No significant abnormality in appearance.							LEM · LB · LBC · LBR · CB · CBC · CBL · LBM ·	
	Q→	_	•							LBMF · CBMF
	R12~4R7:									Temperature : −40±2°C
	30min.									Duration: 1000 hrs
	5R6~330:									Recovery: At least 2 hrs of recovery under
	25min.									the standard condition after the
	390~820:									test, followed by the measure-
	20min.									ment within 48 hrs.
	101:15min.									ment within 48 nrs.
24.Standard condition	Standard test	Standard test condition: Unless otherwise specified,temperature is 20±15°C, and 65±20% of relative humidity.When there a							hen there are	
	question cond	question concerning measurement result : In order to provide correlation date, the test shall be condition of 20±2°C of temperature,								
	65±5% relative humidity.									
	Inductance is in accordance with our measured value.									
	<u> </u>									I

Stages	Precautions	Technical considerations					
1.Circuit Design	Operating environment, 1. The products described in this specification are intended for use in general electronic equipment, (office supply equipment, telecommunications systems, measuring equipment, and household equipment). They are not intended for use in mission-critical equipment or systems requiring special quality and high reliability (traffic systems, safety equipment, aerospace systems, nuclear control systems and medical equipment including life-support systems,) where product failure might result in loss of life, injury or damage. For such uses, contact TAIYO YUDEN Sales Department in advance.						
2.PCB Design	Land pattern design 1.Please contact any of our offices for a land pattern, and refer to a recommended land pattern of a right figure or specifications.	PRECAUTIONS [Recommended Land Patterns] Surface Mounting · Mounting and soldering conditions should be checked beforehand. · Applicable soldering process to this products is reflow soldering only. · Recommended Land Patterns TYPE A B C 1608 0.55 0.7 1.0					
		MF1608 0.55 0.8 1.0 2012 0.7 0.8 1.45 2016 0.7 0.8 1.8 2518 0.8 1.2 2.0 LEM2520 0.9 1.5 1.5 3218 1.0 1.6 2.0 3225 1.0 1.6 2.7					
 Considerations for automatic placement 	Adjustment of mounting machine 1.Excessive impact load should not be imposed on the products when mounting onto the PC boards. 2.Mounting and soldering conditions should be checked beforehand.	When installing products, care should be taken not to apply distortion stress as i may deform the products.					
4.Soldering	Wave soldering (LEM Type only) 1.For wave soldering, please apply conditions meeting the range of the specifed conditions in our catalog or the relevant specifications. Reflow soldering (LB and CB Types) 1.For reflow soldering with either leaded or lead-free solder, the profile specified in "point for controlling" is recommended. Reflow soldering (LEM) 1.For reflow soldering, please apply conditions meeting the range of the specified conditions in our catalog or the relevant specifications.	1. Components can be damaged by excessive heat whre soldering conditions exceed the specified range. 1. Reflow profile 300 250 250 80°C Pre-heat zone 150°C 90±30 sec 30±10 sec 30±10 sec					
	Recommended conditions for using a soldering iron 1.Put the soldering iron on the land-pattern. Soldering iron's temperature-Below 350°C Duration-3 secons or less The soldering iron shoud not come in contact with inductor directly.	1.Components can be damaged by excessive heat whre soldering conditions exceed the specified range.					
5.Cleaning	Cleaning conditions LEM Type, LB Type, CB Type 1.Washing by supersonic waves shall be avoided.	LEM Type, LB Type, CB Type 1.If washing by supersonic waves, supersonic waves may cause broken products.					
6.Handling	Handling 1.Keep the inductors away from all magnets and magnetic objects. Breakaway PC boards (splitting along perforations)	There is a case that a characteristic varies with magnetic influence.					
	1.When splitting the PC board after mounting inductors, care should be taken not to give any stresses of deflection or twisting to the board. 2.Board separation should not be done manually, but by using the appropriate devices. Mechanical considerations	Planning pattern configurations and the position of products should be careful performed to minimize stress.					
7 Storage conditions	1.Please do not give the inductors any excessive mechanical shocks. Charges	There is a case to be damaged by a mechanical shock.					
7.Storage conditions	Storage 1.To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled. •Recommended conditions Ambient temperature 0~40°C Humidity Below 70% RH The ambient temperature must be kept below 30°C Even under ideal storage conditions, solderability of products electrodes may decrease as time passes. For this reason, LE type inductors should be used within one year from the time of delivery. LB type Please should be used within 6 months from the time of delivery. LE type	Under a high temperature and humidity environment, problems suchas reduce solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place.					